



NOTES:

- 1) R8 for test purposes only

ASSEMBLY:

- 1) L1, start of winding points to switch node

Revision History	
Revision	Notes
A	*** preliminary ***
B	adjusted loop and RC snubber

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Number: PMP10123 | Rev: B  
 SVN Rev: Not in version control  
 Drawn By:  
 Engineer: B.Geck

Designed for: Public Release | Mod. Date: 12/4/2014  
 Project Title: sync buck w/ TPS57112  
 Sheet Title:  
 Assembly Variant: Variant name not interpreted | Sheet: 1 of 1  
 File: PMP10123RevB.SchDoc | Size: A4  
 Contact: <http://www.ti.com/support>



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